

Storage A+ Server ASG-1115S-NE3X12R



More details here

Key Applications

Software-defined Storage, In-Memory Computing, Data Intensive HPC, Private & Hybrid Cloud, NVMe Over Fabrics Solution,

Key Features

- Single Socket SP5 AMD EPYC™ 9004 Series processors. Up to 300W TDP.;
- Supports 24 DIMMs with 2DPC, up to 9TB memory capacity with 24 DIMMs of 384GB 3DS RDIMM/RDIMM DDR5 ECC memory;
- Two PCIe 5.0 x16 slots & two AIOM connectors (OCP 3.0 SFF compliant);
- 4x E3.S CXL (16.8mm) + 8x hot-swap E3.S (7.5mm) NVMe drive bays;
- Redundant Titanium 1600W Power Supplies;



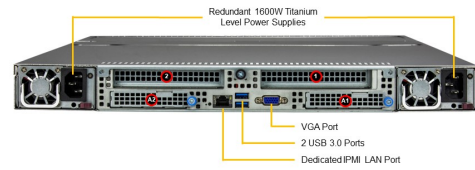
Form Factor	1U Rackmount Enclosure: 438.4 x 43.6 x 773.25mm (17.2" x 1.7" x 30.4") Package: 604.774 x 199.898 x 1029.97mm (23.81" x 7.87" x 40.55")
Processor	Single processor(s) AMD EPYC™ 9004/9005 Series Processors (* AMD EPYC™ 9005 Series drop-in support requires board revision 2.x) Up to 96C/192T
System Memory	Slot Count: 24 DIMM slots/12 Channels Max Memory (1DPC): Up to 3TB 4800MT/s ECC DDR5 RDIMM (AMD EPYC™ 9004 Series Processor) Max Memory (2DPC): Up to 6TB 4000MT/s ECC DDR5 RDIMM (AMD EPYC™ 9004 Series Processor) Max Memory (1DPC): Up to 4.5TB 5200MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor) Max Memory (2DPC): Up to 9TB 4400MT/s ECC DDR5 RDIMM (AMD EPYC™ 9005 Series Processor)
Drive Bays Configuration	Default: Total 12 bays <ul style="list-style-type: none"> • 8 front hot-swap E3.S 1T PCIe 5.0 x4 NVMe drive bays • 4 front fixed E3.S 2T PCIe 5.0 x8 CXL Type 3 drive bays M.2: 1 M.2 PCIe 3.0 x2 NVMe slot (M-key 2280/22110) 1 M.2 PCIe 3.0 x4 NVMe slot (M-key 2280/22110)
Expansion Slots	PCI-Express (PCIe) Configuration: Default <ul style="list-style-type: none"> • 2 PCIe 5.0 x16 FHHL slots • 2 PCIe 5.0 x16 AIOM slots (OCP 3.0 compatible) CXL Support: Up to 4 CXL 2.0 x8 Type 3 devices
On-Board Devices	Chipset: AMD System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 ports(rear) 2 USB 3.0 ports(front) Video: 1 VGA port

(Front View – System)



Drive Bay	Description
1-4	E3 S(2T) NVMe CXL Drive Bays
5-10	Hot-swap E3 S(1T) NVMe Drive Bays

(Rear View – System)



Slot	Slot Description
1-2	PCIe 5.0 x16 FH
3-4	PCIe 5.0 x16 AOM

System Cooling

Fans: 8 Heavy Duty 4cm Fan(s)

Power Supply

1x 1600W Redundant Titanium Level (96%) power supply

System BIOS

BIOS Type: AMI 32MB SPI Flash EEPROM

Management

SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!

PC Health Monitoring

CPU: Monitors for CPU Cores, Chipset Voltages, Memory
 4+1 Phase-switching voltage regulator

FAN: Fans with tachometer monitoring
 Status monitor for speed control
 Pulse Width Modulated (PWM) fan connectors

Temperature: Monitoring for CPU and chassis environment
 Thermal Control for fan connectors

Voltage: +1.8V, +12V, +3.3V, +5V, +5V standby, 10 -fan status, 3.3V standby, HT, Memory, VBAT

Dimensions and Weight

Weight: Gross Weight: 68.74 lbs (31.2 kg)
 Net Weight: 48 lbs (21.8 kg)
 Available Color: Silver

Operating Environment

RoHS Compliant

Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F)
 Non-operating Temperature: -40°C to 60°C (-40°F to 140°F)
 Operating Relative Humidity: 8% to 90% (Non-condensing)
 Non-operating Relative Humidity: 8% to 95% (Non-condensing)

Motherboard
[Super H13SSF](#)
Chassis
CSE-126E32-R1K62P